



AT A GLANCE

Ultra-fast, low-loss and flexible electrical interconnects for opto-electrical packaging.



Features

Polymer embedded electrical coplanar waveguides.

- Bandwidth > 200GHz
- Customized design
- mm to cm scale

Applications

High speed flexible electrical chip to chip interconnect:

- Driver-to-LD
- PD-to-TIA

Technical Background

Ultra-fast, low-loss and flexible electrical coplanar waveguides for interconnecting drivers to laser and photo detectors to transimpedance amplifiers (TIAs) with bandwidths exceeding 200 GHz.

Fabricated on wafer scale.

Customized design available.

References

International R&D projects

PHOENICS

POETICS

POLYNICES

QSNP

Qu-Test / Qu-Pilot

SPRINTER

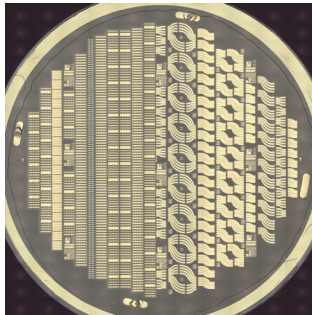
TERA 6G

TERAMEASURE

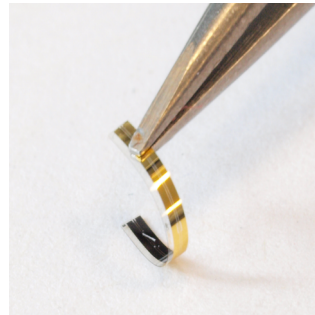
TERAWAY

(funded by EU commission)

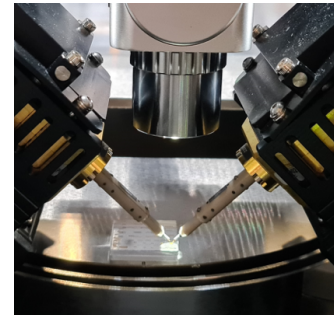
Characteristics



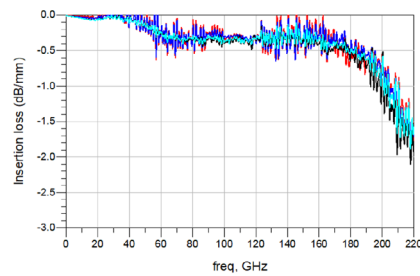
*Fabrication on wafer scale,
customized design*



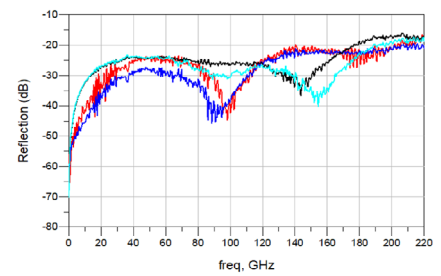
Flexible electrical interconnects



RF characterization set-up



Transmission: >> 200 GHz



Reflection: <-20 dB

Applications



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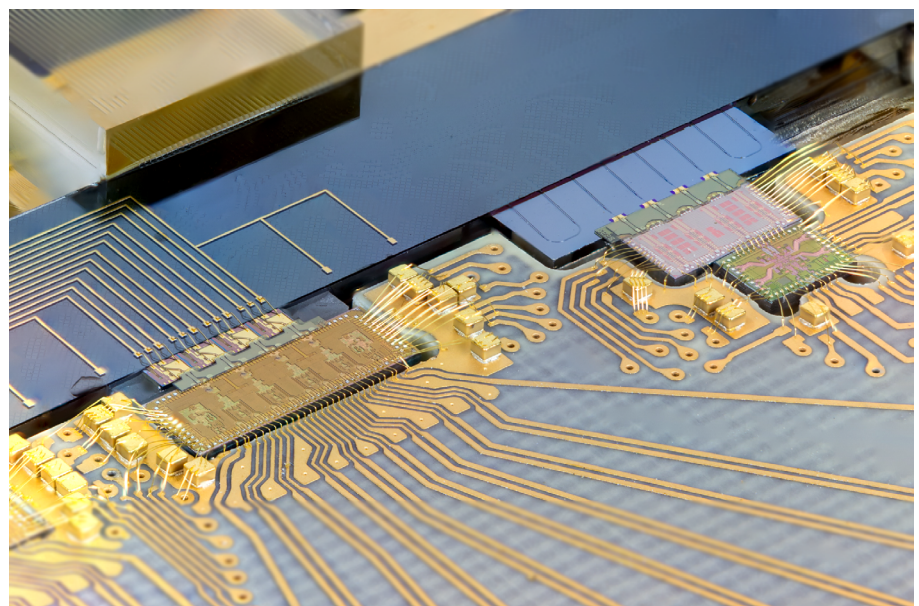
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1.6 Tb/s optical transceiver with FlexLines for intra datacenter connectivity (EU POETICS).